

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-8 (Canceled).

Claim 9 (Original): A power module comprising:

a first substrate with a power semiconductor device mounted thereon;

a second substrate with a control circuit for controlling said power semiconductor

device formed thereon;

a smoothing capacitor electrically connected to said power semiconductor device for

smoothing a voltage to be externally supplied to said power semiconductor device; and

a case including a case frame and a case lid, said case having an interior in which said

first substrate, said second substrate and said smoothing capacitor are disposed.

Claims 10-15 (Canceled).

Claim 16 (Currently Amended): The power module according to claim 9, further comprising:

a heat sink for dissipating heat generated from said first substrate, said first substrate and said case frame being placed on said heat sink,

wherein said smoothing capacitor is disposed on said heat sink.

Claim 17 (Original): The power module according to claim 9,

wherein said smoothing capacitor is a ceramic capacitor.